

Set-Gel 700CC

Set-Gel 700CC is a flexible, non-abrasive filled 100% solids epoxy system. It is a resin that exhibits low coefficient of thermal expansion and exceptional shock resistance. **Set-Gel 700CC** is designed in such a way that the mix ratio is 1:1 by volume. It is a room temperature cure, has excellent moisture resistance, and is also machine dispensable.

Properties-Uncured:

	Part A	Part B
Color, Visual	Clear	Black
Viscosity, cps @ 25 °C	600	2500
Mixed Viscosity, cps	900 to 1500	
Specific Gravity	1.12	
Mix Ratio, volume	1:1	
Pot Life @25°C, hours (Fast System)	15 –20 minutes (100 grams)	
Pot Life @ 25°C, Hours (Slow System)	80 to 90 minutes (100 grams)	
Shelf Life @25°C, months	6	

Physical Properties-Cured:

Durometer (Shore A)	70
Tensile Strength, psi	3500
Tensile Elongation, %	25
Coefficient of Thermal Expansion, °C	7 X 10⁻⁶
Thermal Conductivity, (BTU-in)/(hr*ft²*F)	3.5
Service Temperature, °C	130

Electrical:

Dielectric Strength, volts/Mil	370
Dielectric Constant, 60 Hz	4.5
Dissipation Factor, 60 Hz	0.08
Volume Resistivity, ohm-cm	7.0 X 10¹⁶

Mixing Instruction:

Pre-mix Part A and Part B separately. Then measure 1:1 by Volume (A to B). Mix thoroughly scraping the sides and bottom of the container. Evacuate and then pour into mold or cavity.

Cure Schedule: Room Temperature cure @ 75 °F with full properties after 24 hours. Demold time @75 °F 4 Hours.

Warranty

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